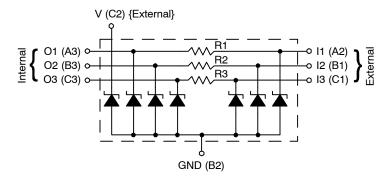
CM6305

EMI Filter with ESD Protection for SIM Card Applications

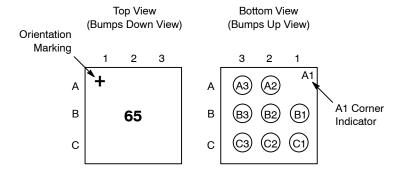
Product Description

The CM6305 is a 3 x 3, 8-bump EMI filter with ESD protection device for SIM card applications in a 0.4 mm pitch CSP form factor. It is fully compliant with IEC 61000-4-2. The CM6305 is also RoHS II compliant.

ELECTRICAL SCHEMATIC



PACKAGE / PINOUT DIAGRAMS





ON Semiconductor®

http://onsemi.com



WLCSP8 CASE 567CE

MARKING DIAGRAM



65 = CM6305 YWW = Date Code

ORDERING INFORMATION

	Device	Package	Shipping [†]
СМ	6305	WLCSP-8 (Pb-Free)	5000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

Table 1. PIN DESCRIPTIONS

Pin	Pin Description		Description	
A2 Channel 1 External		A3	Channel 1 Internal	
B1	B1 Channel 2 External		Channel 2 Internal	
C1	Channel 3 External	С3	Channel 3 Internal	
B2	GND	C2	V External	

CM6305

ELECTRICAL SPECIFICATIONS AND CONDITIONS

Table 2. PARAMETERS AND OPERATING CONDITIONS

Parameter	Rating	Units
Storage Temperature Range	-55 to +150	°C
Operating Temperature Range	-40 to +85	°C
Power Dissipation at 70°C per Channel	60	mW

Table 3. ELECTRICAL OPERATING CHARACTERISTICS (Note 1)

Symbol	Parameter	Conditions	Min	Тур	Max	Units
R ₁	Resistance		80	100	120	Ω
R ₂	Resistance		37.6	47	56.4	Ω
R ₃	Resistance		80	100	120	Ω
I _{LEAK}	Leakage Current per Channel	V _{IN} = 3.0 V		10	100	nA
С	Capacitance on Filter Channels 1, 2 and 3	At 1 MHz, V _{IN} = 0 V	8	10	12	pF
	Capacitance on Clamp Channel (pin C2)	At 1 MHz, V _{IN} = 0 V	8	10	12	pF
V _B	Breakdown Voltage (Positive)	I _R = 1 mA	6	7	9	V
V _{ESD}	ESD Protection Peak Discharge Voltage at A2, B1 and C1 pins a) Contact Discharge per IEC 61000-4-2 standard b) Air Discharge per IEC 61000-4-2 standard	(Note 2)	±8 ±15			kV
	ESD Protection Peak Discharge Voltage at C2 pin a) Contact Discharge per IEC 61000-4-2 standard b) Air Discharge per IEC 61000-4-2 standard	(Note 2)	±15 ±15			kV
	ESD Protection Peak Discharge Voltage at A3, B3 and C3 pins a) Contact Discharge per IEC 61000-4-2 standard b) Air Discharge per IEC 61000-4-2 standard	(Note 2)	±2 ±2			kV

Table 4. CSP TAPE AND REEL SPECIFICATIONS †

Part Number	Chip Size (mm)	Pocket Size (mm) B ₀ X A ₀ X K ₀	Tape Width W	Reel Dia.	Qty Per Reel	P ₀	P ₁
CM6305	1.16 X 1.16 X 0.60	1.27 X 1.27 X 0.69	8 mm	178 mm (7")	5000	4 mm	4 mm

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

^{1.} All parameters specified at T_A = 25°C unless otherwise noted. 2. Standard IEC 61000–4–2 with $C_{Discharge}$ = 150 pF, $R_{Discharge}$ = 330 Ω .

CM6305

RF CHARACTERISTICS

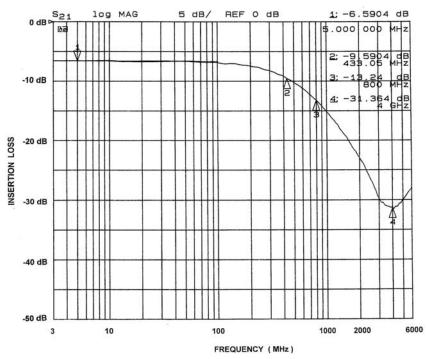


Figure 1. Insertion Loss, Filter 1 (pins A2, A3) and Filter 3 (pins C1, C3) (Bias = 0 V, T_A = 25°C)

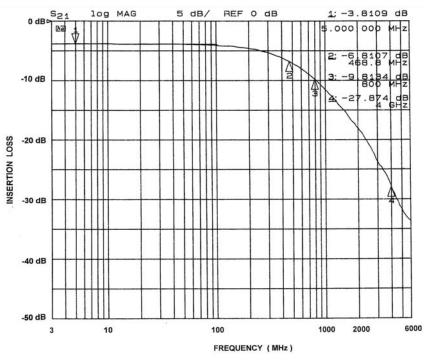


Figure 2. Insertion Loss, Filter 2 (pins B1, B3) (Bias = 0 V, T_A = 25°C)



WLCSP8, 1.16x1.16 CASE 567CE-01 ISSUE O

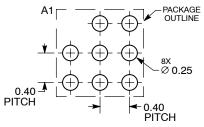
DATE 27 JUL 2010



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

	MILLIMETERS			
DIM	MIN	MAX		
Α	0.57	0.63		
A1	0.17	0.24		
A2	0.41 REF			
b	0.24	0.29		
D	1.16 BSC 1.16 BSC 0.40 BSC			
E				
e				

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PIN A1 REFERENCE	D A B
2X 0.05 C	
2X \(\triangle 0.05 \) C	TOP VIEW
	A2 A A SIDE VIEW SEATING PLANE
8x Ø b 0.05 C A B 0.03 C B A	e e e e e e e e e e e e e e e e e e e

DOCUMENT NUMBER: 98AON50308E Electronic versions are uncontrolled except when accessed directly Printed versions are uncontrolled except when stamped "CONTROL			
DESCRIPTION:	WLCSP8, 1.16X1.16		PAGE 1 OF 1

ON Semiconductor and at a trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.

onsemi, ONSEMI, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries. onsemi owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of onsemi's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. Onsemi reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and onsemi makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using onsemi products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications provided by onsemi. "Typical" parameters which may be provided in onsemi data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. onsemi does not convey any license under any of its intellectual property rights nor the rights of others. onsemi products are not designed, intended, or authorized for use as a critical component in life support systems or any EDA class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer pu

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT: Email Requests to: orderlit@onsemi.com

onsemi Website: www.onsemi.com

TECHNICAL SUPPORT North American Technical Support: Voice Mail: 1 800-282-9855 Toll Free USA/Canada Phone: 011 421 33 790 2910

Europe, Middle East and Africa Technical Support:

Phone: 00421 33 790 2910

For additional information, please contact your local Sales Representative